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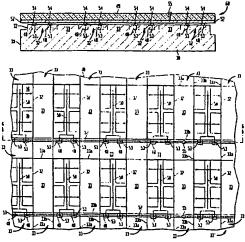
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(54) Title: SEMICONDUCTOR ARRANGEMENT



(57) Abstract: A semiconductor packaging arrangement, or module, includes a printed circuit board having an electrical interconnect thereon and a semiconductor package mounted to the printed circuit board. The semiconductor package includes a fractional portion of a semiconductor wafer having a plurality of integrated circuit chips thereon, such chips being separated by regions in the fractional portion of the wafer. The fractional portion of the wafer has a plurality of electrical contacts electrically connected to the chips. The package also includes a dielectric member having an electrical conductor thereon. The electrical conductor are electrically connected to the plurality of electrical contacts of the plurality of chips to electrically interconnect such plurality of chips with portions of the electrical conductor spanning the regions in the fractional portion of the wafer. A connector is provided for electrically connecting the electrical conductor of the package to the electrical interconnect of the printed circuit board.

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A. CLASSIFICATION OF SUBJECT MATTER IPC 7 H01L23/528 H01L H01L23/50 H01L21/66 H01L27/10 H01L21/82 According to International Patent Classification (IPC) or to both national classification and IPC B. FIELDS SEARCHED Minimum documentation searched (classification system followed by classification symbols) IPC 7 H01L Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched Electronic data base consulted during the international search (name of data base and, where practical, search terms used) PAJ, EPO-Internal C. DOCUMENTS CONSIDERED TO BE RELEVANT Relevant to claim No. Category 9 Citation of document, with indication, where appropriate, of the relevant passages 1,6-9 PATENT ABSTRACTS OF JAPAN X vol. 013, no. 539 (E-853). 30 November 1989 (1989-11-30) -& JP 01 220843 A (NEC CORP) 4 September 1989 (1989-09-04) abstract 3,4 Α 2,5 US 6 055 655 A (MOMOHARA TOMOMI) Y 25 April 2000 (2000-04-25) 1,3,4, the whole document A 6-9 X Further documents are listed in the continuation of box C. Patent family members are listed in annex. Special categories of cited documents: "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the *A* document defining the general state of the art which is not considered to be of particular relevance "E" earlier document but published on or after the international "X" document of particular relevance; the claimed invention filing date cannot be considered novel or cannot be considered to "L" document which may throw doubts on priority claim(s) or involve an inventive step when the document is taken alone which is cited to establish the publication date of another citation or other special reason (as specified) "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such docu document reterring to an oral disclosure, use, exhibition or ments, such combination being obvious to a person skilled in the art. other means document published prior to the international filing date but later than the priority date claimed *&* document member of the same patent family Date of the actual completion of the international search Date of mailing of the international search report 14 February 2002 22/02/2002 Name and mailing address of the ISA Authorized officer European Patent Office, P.B. 5818 Patentlaan 2 NL - 2280 HV Rijswijk Tel. (+31-70) 340-2040, Tx. 31 651 epo ni, Albrecht, C Fax: (+31-70) 340-3016

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